

AMENDMENT TO SPECIFICATION

Please amend paragraph [0011] on page 3 as follows:

[0011] In accordance with an aspect of the present invention, there is provided a semiconductor memory device having semiconductor memory chips, each semiconductor memory chip comprising: a plurality of memory banks ~~to be being~~ independently accessed, each memory bank having a plurality of memory blocks, wherein at least two memory blocks, which are neighbored to each other in the same memory bank, have ~~the~~ different numbers of unit memory blocks, so that each bank has a non-rectangular shape.

Please amend paragraphs [0027] and [0031] on page 6 as follows:

[0027] FIG. 12 is a schematic plane view showing interconnection between power lead frames and pads to be wire-bonded to each other in accordance with the second embodiment of the present invention shown in FIG. 6; and

[0031] FIG. 3 is a plane view showing the 512-Mbit DDR SDRAM (hereinafter, referred to as a semiconductor memory chip) in accordance with the first embodiment of the ~~present~~present invention.

Please amend paragraph [0065] on page 14 as follows:

[0065] FIG. 12 is a schematic plane view showing interconnection between power lead frames and pads to be ~~wire-bonded~~wire-bonded to each other in accordance with the second embodiment of the present invention shown in FIG. 6.